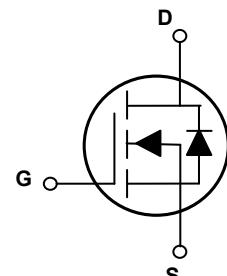
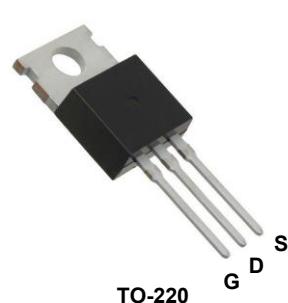


## Main Product Characteristics

$V_{DS}$	60V
$R_{DS(ON)}$	7mΩ (Max.)
$I_D$	80A



## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFH0680 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	80	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		56.5	
Drain Current-Pulsed	$I_{DM}$	320	A
Single Pulse Avalanche Energy <sup>5</sup>	$E_{AS}$	390	mJ
Maximum Power Dissipation	$P_D$	110	W
Derating Factor		0.73	W/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Case <sup>2</sup>	$R_{\theta JC}$	1.36	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +175	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +175	$^\circ\text{C}$

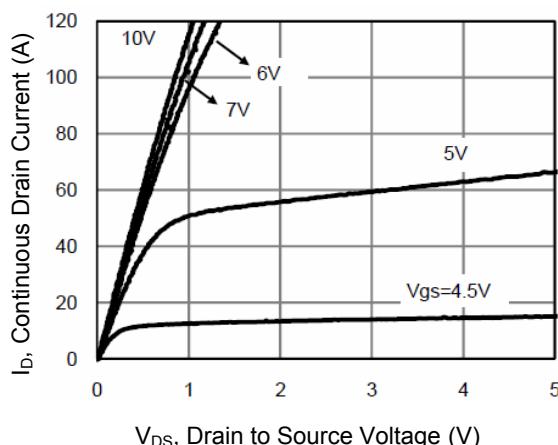
**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	-	-	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance <sup>3</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	-	6	7	$\text{m}\Omega$
Gate Threshold Voltage <sup>3</sup>	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	2	2.8	4	V
Forward Transconductance <sup>3</sup>	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=20\text{A}$	20	-	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>4</sup>	$Q_g$	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=20\text{A}$ $V_{\text{GS}}=10\text{V}$	-	90	-	nC
Gate-Source Charge <sup>4</sup>	$Q_{\text{gs}}$		-	9	-	
Gate-Drain Charge <sup>4</sup>	$Q_{\text{gd}}$		-	18	-	
Turn-On Delay Time <sup>4</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=30\text{V}, R_{\text{L}}=1\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=3\Omega$	-	8.5	-	nS
Rise Time <sup>4</sup>	$t_r$		-	7	-	
Turn-Off Delay Time <sup>4</sup>	$t_{\text{d}(\text{off})}$		-	40	-	
Fall Time <sup>4</sup>	$t_f$		-	15	-	
Input Capacitance <sup>4</sup>	$C_{\text{iss}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V},$ $F=1\text{MHz}$	-	4000	-	pF
Output Capacitance <sup>4</sup>	$C_{\text{oss}}$		-	290	-	
Reverse Transfer Capacitance <sup>4</sup>	$C_{\text{rss}}$		-	210	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Diode Forward Voltage <sup>3</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=20\text{A}$	-	-	1.2	V
Continuous Source Current <sup>2</sup>	$I_{\text{S}}$	-	-	-	80	A
Reverse Recovery Time <sup>3</sup>	$t_{\text{rr}}$	$T_J=25^\circ\text{C}, I_F=20\text{A},$ $dI/dt=100\text{A}/\mu\text{s}$	-	32	-	nS
Reverse Recovery Charge <sup>3</sup>	$Q_{\text{rr}}$		-	45	-	nC
Forward Turn-On Time	$t_{\text{on}}$	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

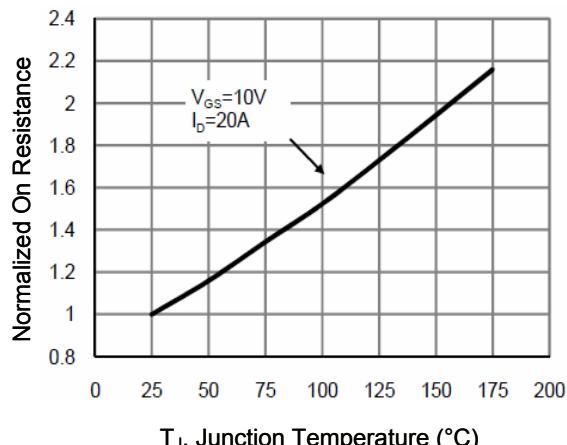
Notes:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. Surface mounted on FR4 board,  $t \leq 10\text{s}$ .
3. Pulse test: Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production.
5. EAS condition:  $V_{\text{DD}}=20\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_{\text{G}}=25\Omega, T_J=25^\circ\text{C}$ .

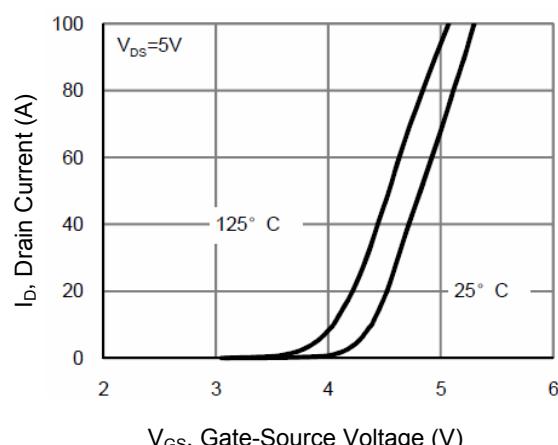
## Typical Electrical and Thermal Characteristic Curves



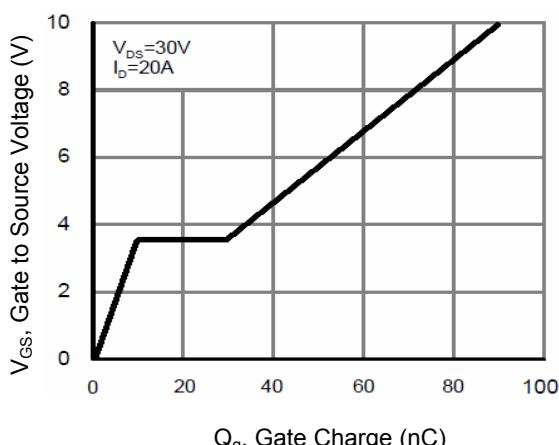
**Figure 1. Typical Output Characteristics**



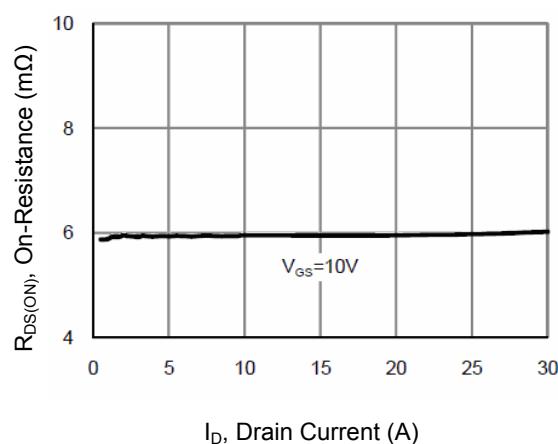
**Figure 2. Normalized  $R_{DS(on)}$  vs.  $T_J$**



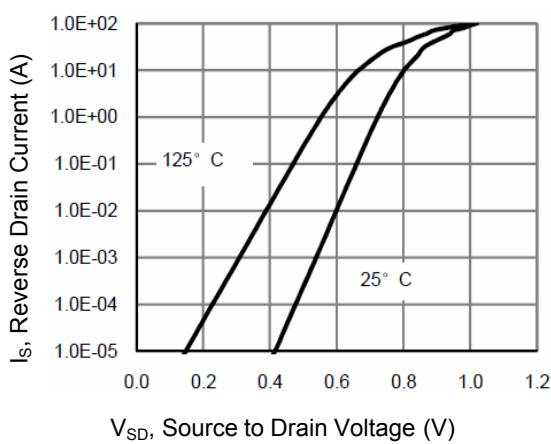
**Figure 3. Transfer Characteristics**



**Figure 4. Gate Charge Characteristics**



**Figure 5.  $R_{DS(on)}$  - Continuous Drain Current**



**Figure 6. Source-Drain Diode Forward**

## Typical Electrical and Thermal Characteristic Curves

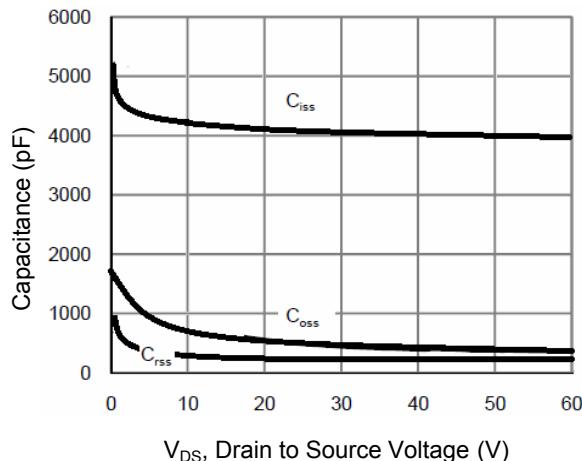


Figure 7. Capacitance Characteristics

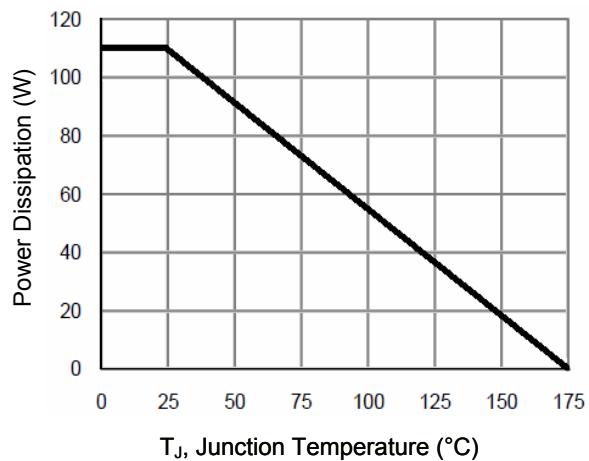


Figure 8. Power Derating

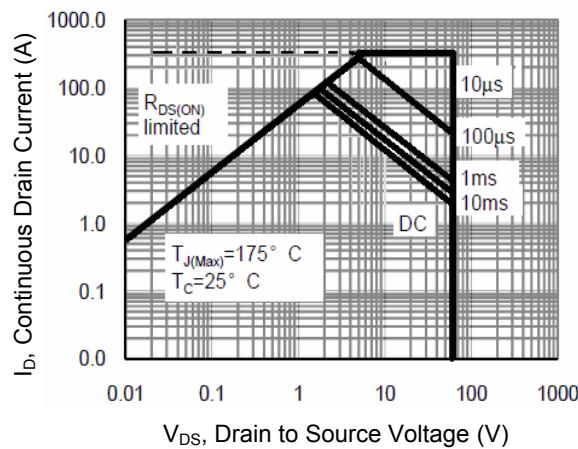


Figure 9. Maximum Safe Operation Area

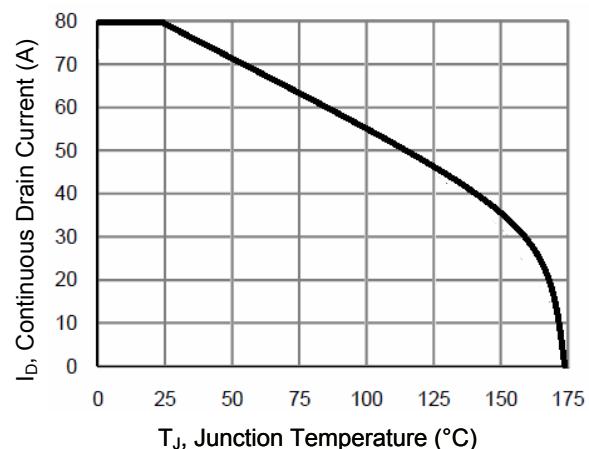


Figure 10. Drain Current - Junction Temperature

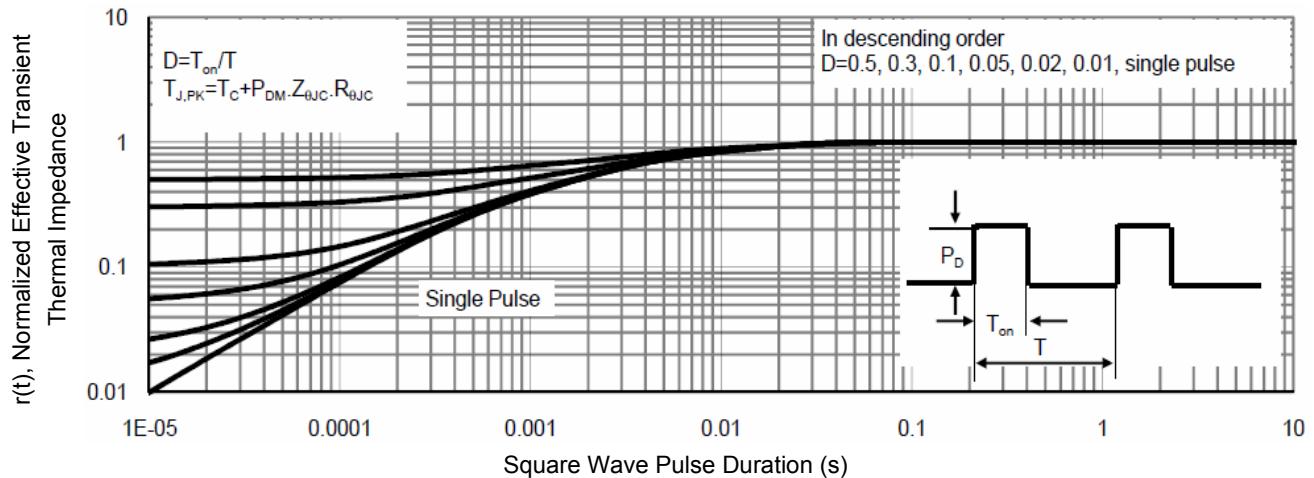
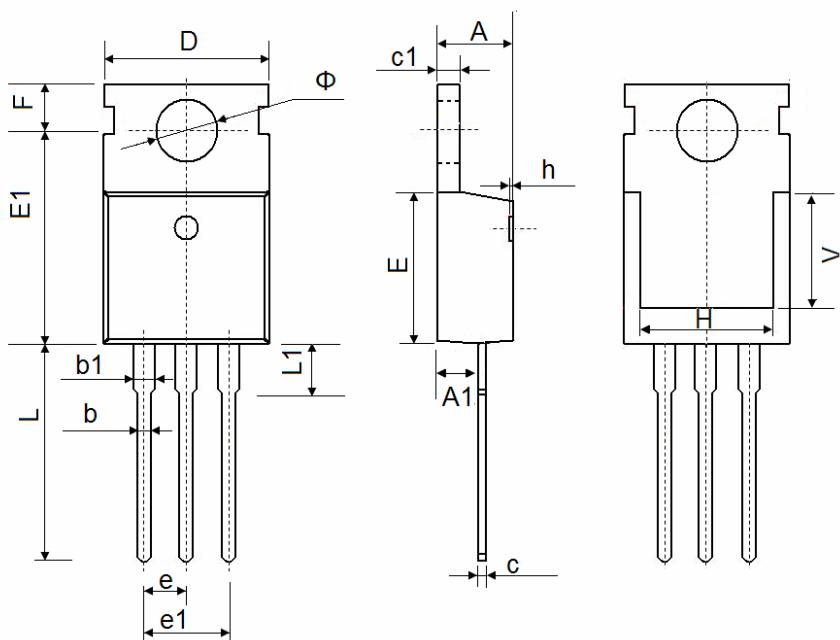


Figure 11. Normalized Maximum Transient Thermal Impedance

### Package Outline Dimensions (TO-220)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP		0.100 TYP	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF		0.295 REF	
Φ	3.400	3.800	0.134	0.150